



2009-2010 Update to sales guidance for Q1

Bernin, France, 22nd June 2009 – Soitec, leader in SOI (Silicon on Insulator) wafer material today announced that rush orders have been received from its main customers showing significant increases to their demand over the first six months of the financial year. Therefore the Group now anticipates a sequential recovery in sales higher than 20% for the first quarter of the financial year 2009-2010. First indications for the second quarter point to a robust level of activity with the potential for further sequential growth, but this needs to be confirmed in the coming months.

In a climate of general industry uncertainty for continuous improvement to end market demand in the second half of the year, the Company maintains its position not to provide sales guidance for the full financial year 2009-2010.

Agenda

Sales for the first quarter will be published on Monday 20 July 2009 after the close of the Paris Stock Exchange.

About the Soitec Group:

The Soitec Group is the world's leading innovator and provider of the engineered substrate solutions that serve as the foundation for today's most advanced microelectronic products. The group leverages its proprietary Smart Cut™ technology to engineer new substrate solutions, such as silicon-on-insulator (SOI) wafers, which became the first high-volume application for this proprietary technology. Since then, SOI has emerged as the material platform of the future, enabling the production of higher performing, faster chips that consume less power.

Today, Soitec produces more than 80 percent of the world's SOI wafers. Headquartered in Bernin, France, with two high-volume fabs on-site, Soitec has offices throughout the United States, Japan and Taiwan, and a new production site in the process of customers' qualification in Singapore.

Two other divisions, Picogiga International (Les Ulis) and Tracit Technologies (Bernin), complete the Soitec Group. Picogiga delivers advanced substrates solutions, including III-V epiwafers and gallium nitride (GaN) wafers, to the compound material world for the manufacture of high-frequency electronics and other optoelectronic devices. Tracit, on the other hand, provides thin-film layer transfer technologies used to manufacture advanced substrates for power ICs and microsystems, as well as generic circuit transfer technology "Smart Stacking" for applications such as image sensors and 3D-integration. Shares of the Soitec Group are listed on Euronext Paris. For more information, visit www.soitec.com.

*SOI: Silicon On Insulator - sSOI: strained Silicon On Insulator

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